

積層造形用 金属粉末

Metal Powder for Additive Manufacturing

FAM Series 積層造形用 純銅及び銅合金粉末

Copper and Copper Alloy Powder for Additive Manufacturing

FAM-QCU

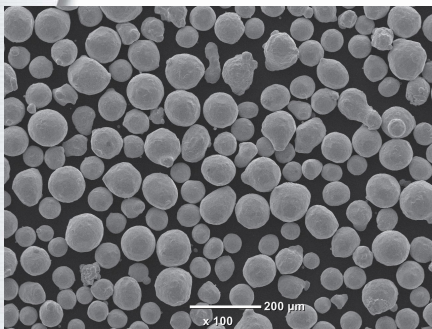
積層造形用純銅粉末

Pure copper powder for PBF and DED

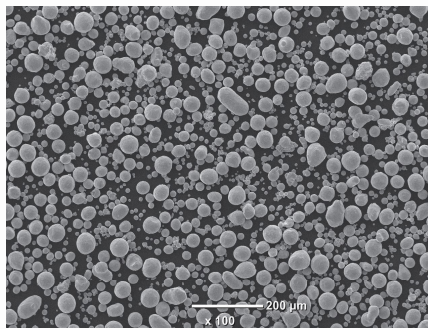
特長 Advantages

ガスアトマイズ法により製造した球状で、流動性のある純銅粉末。
高純度銅により導電部品や放熱部品への適用が可能。

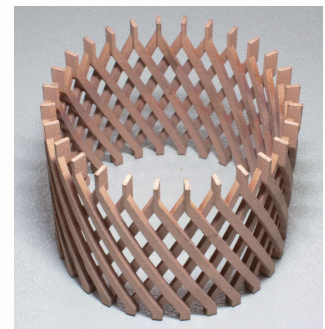
The spherically formed gas atomized pure copper powder has excellent fluidity for additive manufacturing.
High-purity copper makes it suitable for use in conductive parts and heat dissipation parts.



PBF-EB FAM-QCU 45-105 μm
(SEM image ×100)



PBF-LB FAM-QCU 10-45 μm
(SEM image ×100)



PBF-LB 造形例
Molding sample for PBF-LB

FAM-G101

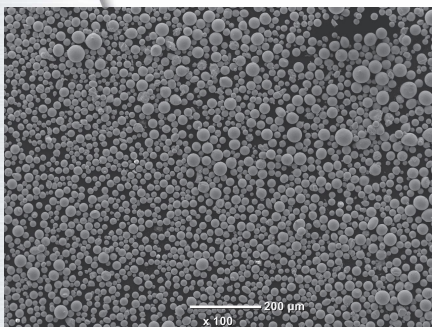
積層造形用銅合金粉末

Copper alloy powder for PBF and DED

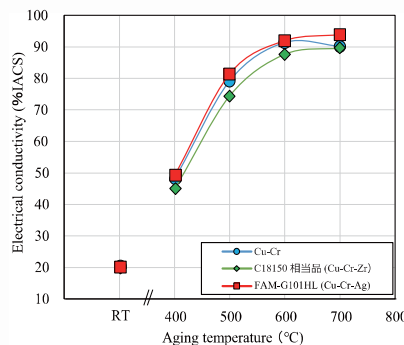
特長 Advantages

ガスアトマイズ法で作製した球状粉末で、波長1060nm近傍のLB熱源に対して高い造形性。
時効処理により高強度と高導電性を発現し、高強度・高導電部品への応用が可能。

The copper alloy powder that is spherically formed by gas atomization method has high formability for LB heat sources with a wavelength of around 1060 nm.
Aging treatment enhances properties suitable for high strength and high electrical conductivity parts.



PBF-LB FAM-G101HL 10-45 μm
(SEM image ×100)



FAM-G101HL 時効処理後の電気伝導性
Electrical conductivity after aging treatment



PBF-LB 造形例
Molding sample for PBF-LB



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福田金属箔粉工業株式会社 HP



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